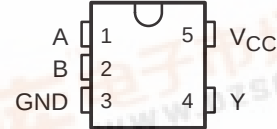


- **Qualification in Accordance With AEC-Q100†**
- **Qualified for Automotive Applications**
- **Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval**
- **Operating Range of 2 V to 5.5 V**
- **Max t_{pd} of 9 ns at 5 V**
- **Low Power Consumption, 20- μ A Max I_{CC}**
- **± 8 -mA Output Drive at 5 V**
- **Schmitt Trigger Action at All Inputs Makes the Circuit Tolerant for Slower Input Rise and Fall Time**
- **ESD Protection Level Per AEC-Q100 Classification**
 - 2000-V (H2) Human-Body Model
 - 200-V (M3) Machine Model
 - 1000-V (C5) Charged-Device Model

† Contact factory for details. Q100 qualification data available on request.

DBV OR DCK PACKAGE
(TOP VIEW)



description/ordering information

The SN74AHC1G08 is a single 2-input positive-AND gate. The device performs the Boolean function $Y = A \cdot B$ or $Y = \overline{A} + \overline{B}$ in positive logic.

ORDERING INFORMATION

T_A	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKINGS§
–40°C to 85°C	SOT (SOT-23) – DBV	Reel of 3000	SN74AHC1G08IDBVRQ1	A08_
	SOT (SC-70) – DCK	Reel of 3000	SN74AHC1G08IDCKRQ1	AE_
–40°C to 125°C	SOT (SOT-23) – DBV	Reel of 3000	SN74AHC1G08QDBVRQ1	A08_
	SOT (SC-70) – DCK	Reel of 3000	SN74AHC1G08QDCKRQ1	AE_

‡ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

§ The actual top-side marking has one additional character that designates the assembly/test site.

FUNCTION TABLE

INPUTS		OUTPUT
A	B	Y
H	H	H
L	X	L
X	L	L

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SN74AHC1G08-Q1

SINGLE 2-INPUT POSITIVE-AND GATE

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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Output voltage range, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	–20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V_{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): DBV package	206°C/W
DCK package	252°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			MIN	MAX	MIN	MAX	UNIT
V _{CC}	Supply voltage		2	5.5	2	5.5	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5		1.5		V
		V _{CC} = 3 V	2.1		2.1		
		V _{CC} = 5.5 V	3.85		3.85		
V _{IL}	Low-level input voltage	V _{CC} = 2 V	0.5		0.5		V
		V _{CC} = 3 V	0.9		0.9		
		V _{CC} = 5.5 V	1.65		1.65		
V _I	Input voltage		0	5.5	0	5.5	V
V _O	Output voltage		0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 2 V	−50		−50		μA
		V _{CC} = 3.3 V ± 0.3 V	−4		−4		mA
		V _{CC} = 5 V ± 0.5 V	−8		−8		
I _{OL}	Low-level output current	V _{CC} = 2 V	50		50		μA
		V _{CC} = 3.3 V ± 0.3 V	4		4		mA
		V _{CC} = 5 V ± 0.5 V	8		8		
Δt/Δv	Input transition rise or fall rate	V _{CC} = 3.3 V ± 0.3 V	100		100		ns/V
		V _{CC} = 5 V ± 0.5 V	20		20		
T _A	Operating free-air temperature	I Suffix	−40	85			°C
		Q Suffix			−40	125	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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SINGLE 2-INPUT POSITIVE-AND GATE

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			–40°C TO 85°C		–40°C TO 125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = –50 µA	2 V	1.9	2		1.9		1.9		V
		3 V	2.9	3		2.9		2.9		
		4.5 V	4.4	4.5		4.4		4.4		
	I _{OH} = –4 mA	3 V	2.58			2.48		2.4		
	I _{OH} = –8 mA	4.5 V	3.94			3.8		3.7		
V _{OL}	I _{OL} = 50 µA	2 V			0.1		0.1		0.1	V
		3 V			0.1		0.1		0.1	
		4.5 V			0.1		0.1		0.1	
	I _{OL} = 4 mA	3 V			0.36		0.44		0.52	
	I _{OL} = 8 mA	4.5 V			0.36		0.44		0.52	
I _I	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1		±1	µA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			1		10		20	µA
C _i	V _I = V _{CC} or GND	5 V		4	10		10		10	pF

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	OUTPUT CAPACITANCE	T _A = 25°C			–40°C TO 85°C		–40°C TO 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A or B	Y	C _L = 15 pF		6.2	8.8	1	10.5		12.5	ns
t _{PHL}					6.2	8.8	1	10.5		12.5	
t _{PLH}	A or B	Y	C _L = 50 pF		8.7	12.3	1	14		16.5	ns
t _{PHL}					8.7	12.3	1	14		16.5	

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	OUTPUT CAPACITANCE	T _A = 25°C			–40°C TO 85°C		–40°C TO 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A or B	Y	C _L = 15 pF		4.3	5.9		7		9	ns
t _{PHL}					4.3	5.9		7		9	
t _{PLH}	A or B	Y	C _L = 50 pF		5.8	7.9		9		11	ns
t _{PHL}					5.8	7.9		9		11	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

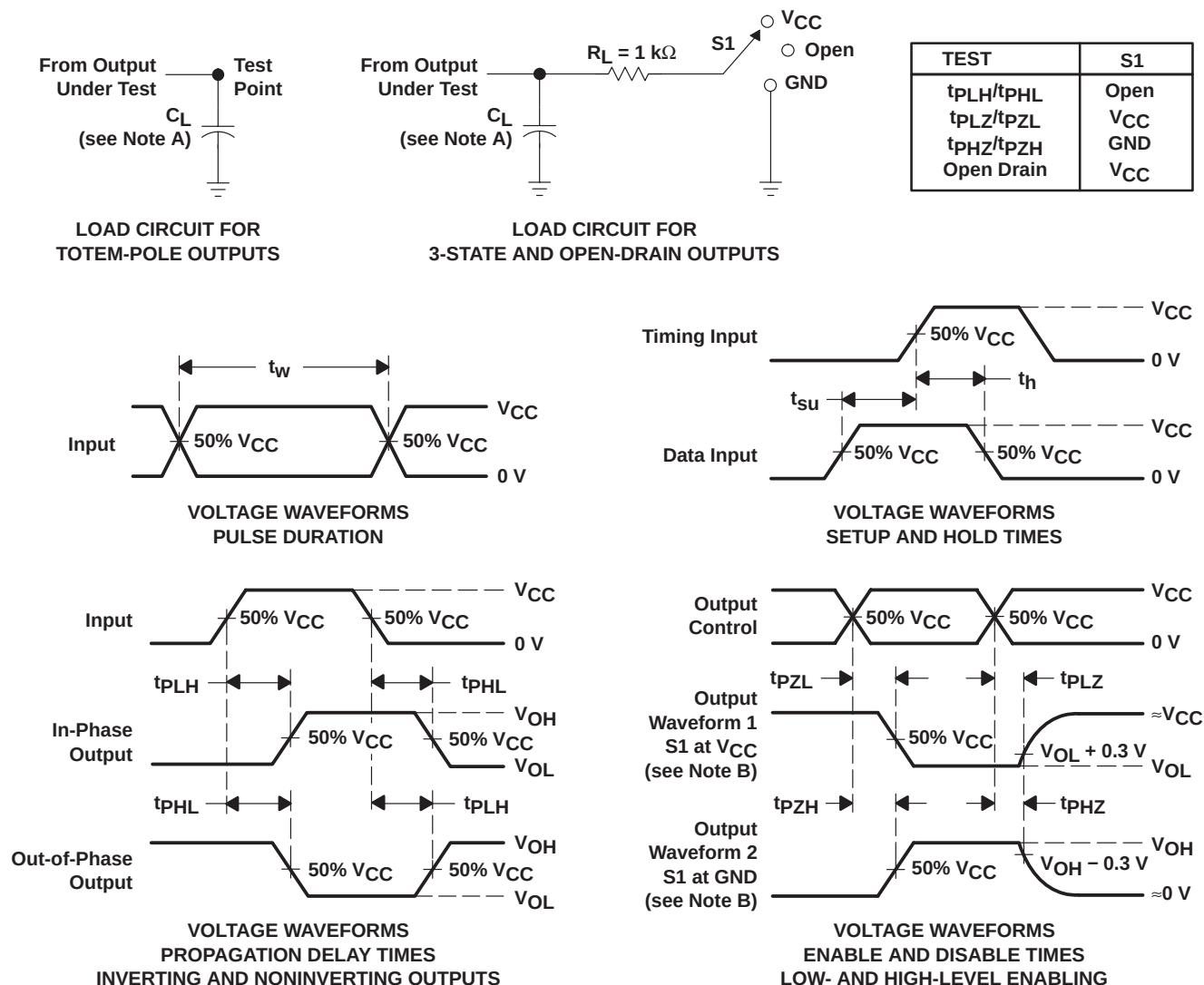
PARAMETER		TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load, f = 1 MHz	18	pF

SN74AHC1G08-Q1

SINGLE 2-INPUT POSITIVE-AND GATE

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PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AHC1G08QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G08QDCKRQ1	ACTIVE	SC70	DCK	5	3000	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

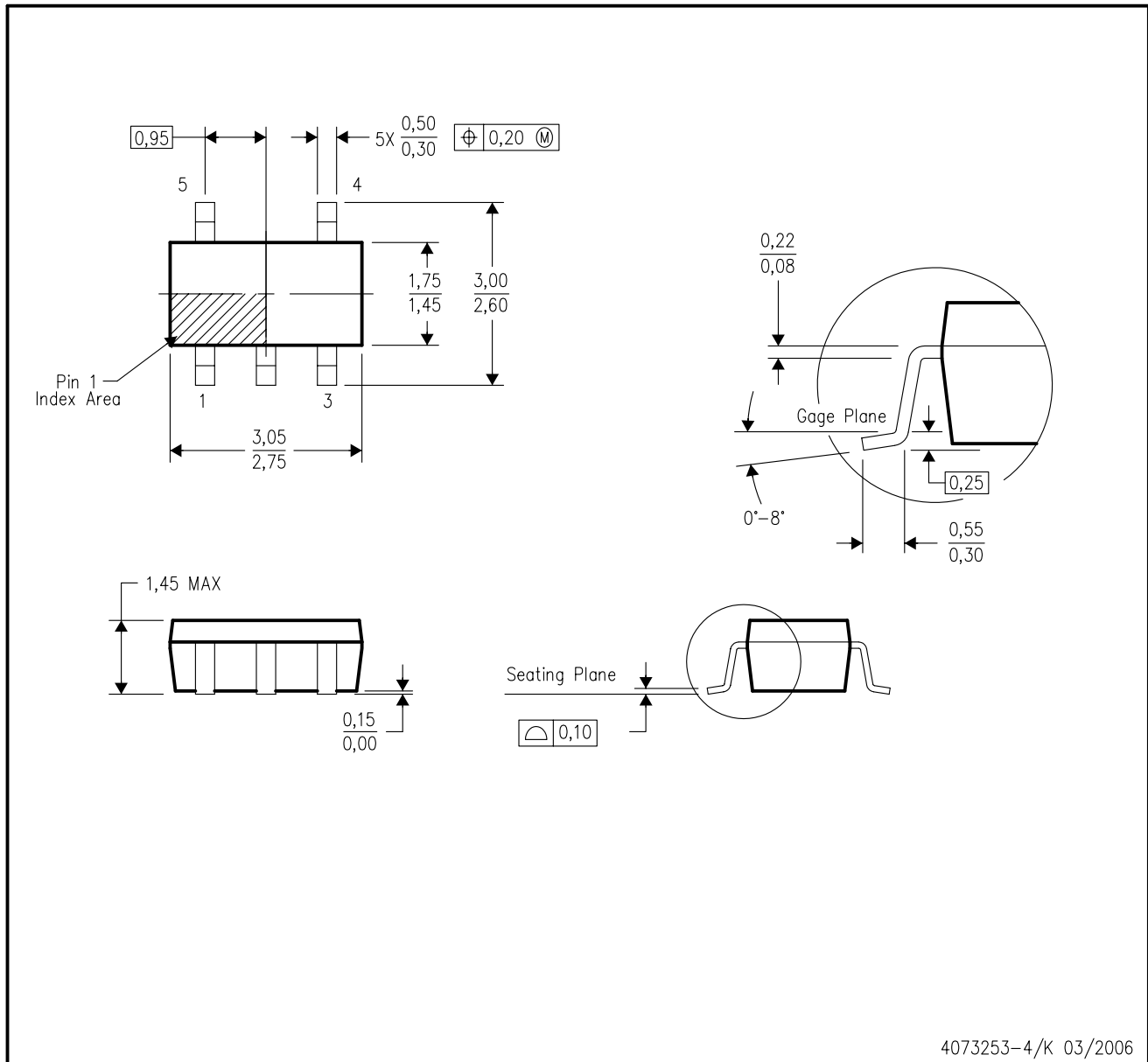
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MECHANICAL DATA

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE

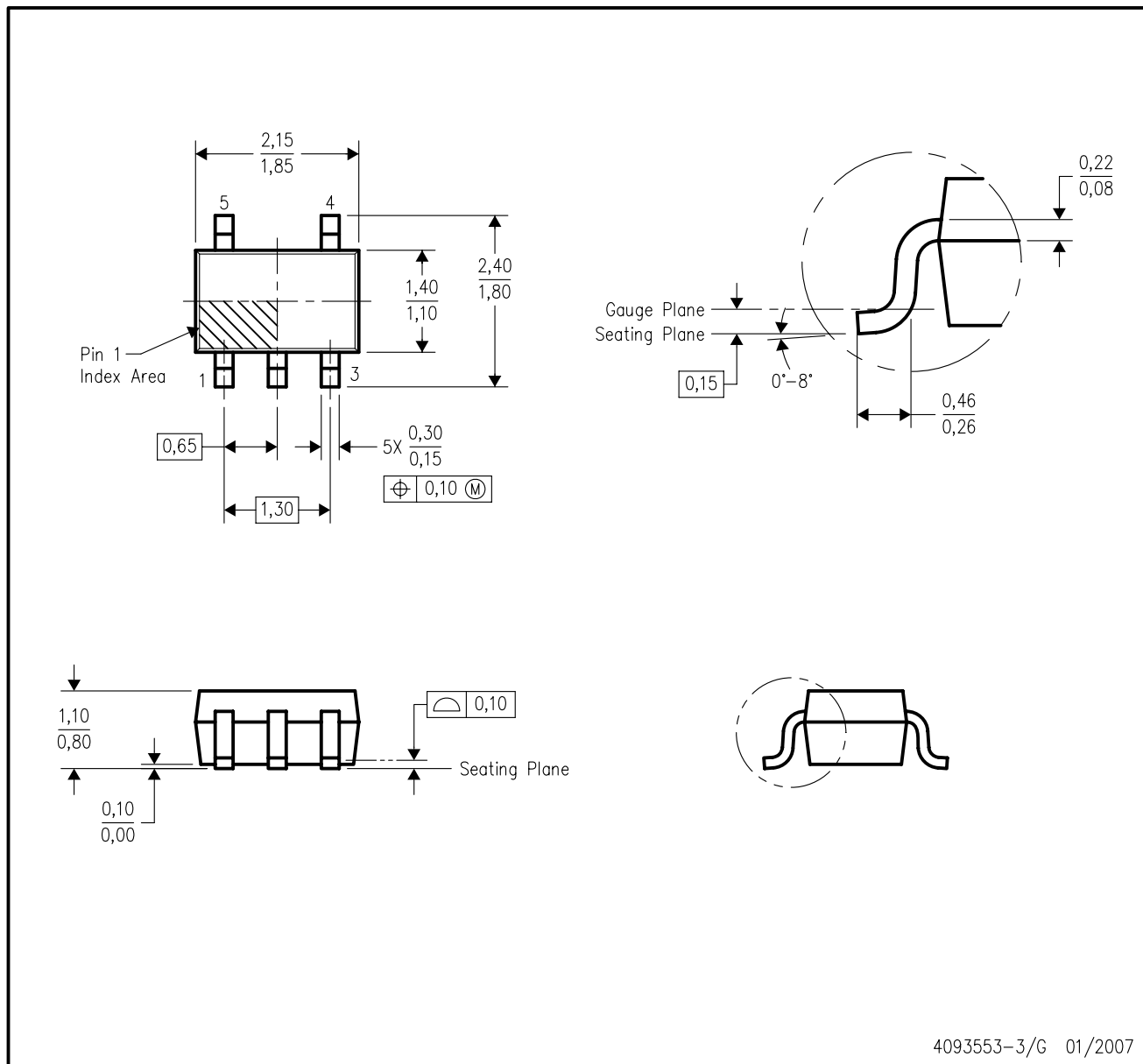


- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - Falls within JEDEC MO-178 Variation AA.

MECHANICAL DATA

DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-203 variation AA.

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